General Description

The SLG59H1403C is designed for OR’ing or manual Power MUX applications. The part comes with two 3 A rated load switches that are well suited for a variety of systems having multiple power sources. The device will automatically detect, select, and seamlessly transition between available inputs. Additionally, manual switching between two power rails allowed.

Features

- Two 3 A load switches with common output
- Two Integrated VGS Charge Pumps
- Wide operating range: 2.8 V to 22 V
- Adjustable output soft start time (SS)
- Low RDS_{ON}: 52 mΩ (typical)
- Adjustable priority
- Accuracy < ±5%
- Adjustable Overvoltage Protection
- Accuracy < ±5%
- Channel status indication (ST)
- Undervoltage Lockout
- True Reverse-Current Blocking
- Protected by thermal shutdown and adjustable current limit
- 1.585 mm x 1.985 mm, 0.4 mm pitch, 20L WLCSP
- Pb-Free / Halogen-Free / RoHS Compliant

Pin Configuration

<table>
<thead>
<tr>
<th>A</th>
<th>B</th>
<th>C</th>
<th>D</th>
<th>E</th>
</tr>
</thead>
<tbody>
<tr>
<td>PR</td>
<td>IN1</td>
<td>IN1</td>
<td>OUT</td>
<td>ST</td>
</tr>
<tr>
<td>OV1</td>
<td>IN1</td>
<td>OUT</td>
<td>OUT</td>
<td>ILIM</td>
</tr>
<tr>
<td>OV2</td>
<td>IN2</td>
<td>OUT</td>
<td>OUT</td>
<td>SS</td>
</tr>
<tr>
<td>SEL</td>
<td>IN2</td>
<td>IN2</td>
<td>OUT</td>
<td>GND</td>
</tr>
</tbody>
</table>

20-pin WLCSP (Bottom View)

Block Diagram
Pin Description

<table>
<thead>
<tr>
<th>Pin #</th>
<th>Pin Name</th>
<th>Type</th>
<th>Pin Description</th>
</tr>
</thead>
<tbody>
<tr>
<td>A1</td>
<td>PR</td>
<td>Input</td>
<td>Analog input which sets the priority to Channel 1. PR is compared to internal reference voltage $V_{REF}$. Connect to GND if not required.</td>
</tr>
<tr>
<td>A2</td>
<td>OV1</td>
<td>Input</td>
<td>Analog input which together with an external resistor divider, is used to set the overvoltage threshold for Channel 1. OV1 is compared to internal reference voltage $V_{REF}$. If $V_{OV1} \geq V_{REF}$, Channel 1 is turned off and returns to normal operation once $V_{OV1} &lt; V_{REF}$. Connect to GND if not used.</td>
</tr>
<tr>
<td>A3</td>
<td>OV2</td>
<td>Input</td>
<td>Analog input which together with an external resistor divider, is used to set the overvoltage threshold for Channel 2. OV2 is compared to internal reference voltage $V_{REF}$. If $V_{OV2} \geq V_{REF}$, Channel 2 is turned off and returns to normal operation once $V_{OV2} &lt; V_{REF}$. Connect to GND if not used.</td>
</tr>
<tr>
<td>A4</td>
<td>SEL</td>
<td>Input</td>
<td>Select makes it possible to override the priority and manually select IN2. SEL is compared to internal reference voltage $V_{REF}$. Connect to GND if not required.</td>
</tr>
<tr>
<td>B1, B2, C1</td>
<td>IN1</td>
<td>Power</td>
<td>Input terminal of load switch Channel 1. Capacitors at IN1 should be rated at a voltage higher than maximum input voltage ever present.</td>
</tr>
<tr>
<td>B3, B4, C4</td>
<td>IN2</td>
<td>Power</td>
<td>Input terminal of load switch Channel 2. Capacitors at IN2 should be rated at a voltage higher than maximum input voltage ever present.</td>
</tr>
<tr>
<td>C2, C3, D1, D2, D3, D4</td>
<td>OUT</td>
<td>Power</td>
<td>Output terminal. Capacitors at OUT should be rated at a voltage higher than maximum input voltage ever present.</td>
</tr>
<tr>
<td>E1</td>
<td>ST</td>
<td>Output</td>
<td>Status is an open-drain, active LOW output. When asserted HIGH, IN1 is selected. When asserted LOW, IN2 is selected. Connect to GND if not required.</td>
</tr>
<tr>
<td>E2</td>
<td>ILIM</td>
<td>Output</td>
<td>A 1%-tolerance resistor connected between ILIM and GND sets the load switch’s active current limit for both channels. Please refer to the Setting the SLG59H1403C’s Active Current Limit section.</td>
</tr>
<tr>
<td>E3</td>
<td>SS</td>
<td>Output</td>
<td>A low-ESR, stable dielectric, ceramic surface-mount capacitor connected from SS pin to GND, sets the $V_{OUT}$ slew rate and overall turn-on time of the SLG59H1403C.</td>
</tr>
<tr>
<td>E4</td>
<td>GND</td>
<td>GND</td>
<td>Ground connection. Connect this pin to system analog or power ground plane.</td>
</tr>
</tbody>
</table>

Ordering Information

<table>
<thead>
<tr>
<th>Part Number</th>
<th>Type</th>
<th>Production Flow</th>
</tr>
</thead>
<tbody>
<tr>
<td>SLG59H1403C</td>
<td>WLCSP-20L</td>
<td>Industrial, -40 °C to 85 °C</td>
</tr>
<tr>
<td>SLG59H1403CTR</td>
<td>WLCSP-20L (Tape and Reel)</td>
<td>Industrial, -40 °C to 85 °C</td>
</tr>
</tbody>
</table>
## Absolute Maximum Ratings

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Description</th>
<th>Conditions</th>
<th>Min.</th>
<th>Typ.</th>
<th>Max.</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>( V_{IN[1,2]} )</td>
<td>Maximum Input Voltage</td>
<td>-0.3 -- 24 V</td>
<td></td>
<td></td>
<td></td>
<td>V</td>
</tr>
<tr>
<td>( V_{OUT} )</td>
<td>Maximum Output Voltage</td>
<td>-0.3 -- 24 V</td>
<td></td>
<td></td>
<td></td>
<td>V</td>
</tr>
<tr>
<td>( V_{OV1}, V_{OV2} )</td>
<td>Maximum Overvoltage Pin Voltage</td>
<td>-0.3 -- 6 V</td>
<td></td>
<td></td>
<td></td>
<td>V</td>
</tr>
<tr>
<td>( V_{PR}, V_{SEL} )</td>
<td>Maximum Control Input Pin Voltage</td>
<td>-0.3 -- 6 V</td>
<td></td>
<td></td>
<td></td>
<td>V</td>
</tr>
<tr>
<td>( V_{ST} )</td>
<td>Maximum Control Output Pin Voltage</td>
<td>-0.3 -- 6 V</td>
<td></td>
<td></td>
<td></td>
<td>V</td>
</tr>
<tr>
<td>( T_S )</td>
<td>Storage Temperature</td>
<td>-65 -- 150 °C</td>
<td></td>
<td></td>
<td></td>
<td>°C</td>
</tr>
<tr>
<td>( ESD_{HBM} )</td>
<td>ESD Protection Human Body Model</td>
<td>2000 -- V</td>
<td></td>
<td></td>
<td></td>
<td>V</td>
</tr>
<tr>
<td>( ESD_{CDM} )</td>
<td>ESD Protection Charged Device Model</td>
<td>500 -- V</td>
<td></td>
<td></td>
<td></td>
<td>V</td>
</tr>
<tr>
<td>MOSFET ( IDS_{PK} )</td>
<td>Peak Current from Drain to Source For no more than 10 continuous seconds out of every 100 seconds</td>
<td>-- -- 3.5 A</td>
<td></td>
<td></td>
<td></td>
<td>A</td>
</tr>
</tbody>
</table>

Note: Stresses greater than those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

## Electrical Characteristics

\( T_A = -40 \, ^\circ C \) to 85 \, ^\circ C, unless otherwise noted.

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Description</th>
<th>Conditions</th>
<th>Min.</th>
<th>Typ.</th>
<th>Max.</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>( V_{IN[1,2]} )</td>
<td>Power Switch Input Voltage</td>
<td>2.8 -- 22 V</td>
<td></td>
<td></td>
<td></td>
<td>V</td>
</tr>
<tr>
<td>( V_{IN[1,2]}(UVLO) )</td>
<td>Undervoltage Lockout Threshold</td>
<td>( V_{IN[1,2]} \uparrow; ) ( V_{IN[1,2]} \downarrow; )</td>
<td>2.5</td>
<td>2.65</td>
<td>2.8</td>
<td>V</td>
</tr>
<tr>
<td>( I_{Q_IN[1,2]} )</td>
<td>Quiescent Current (IN[1,2] powering OUT)</td>
<td>OUT = Open, ( V_{PR} &lt; V_{REF};</td>
<td>V_{IN1}-V_{IN2}</td>
<td>&lt; 1 , V )</td>
<td>--</td>
<td>300</td>
</tr>
<tr>
<td>( I_{STBY_IN[1,2]} )</td>
<td>Standby Current (IN[1,2] not powering OUT)</td>
<td>( V_{OUT} = V_{IN[1,2]}; ) ( V_{PR} &lt; V_{REF};</td>
<td>V_{IN1}-V_{IN2}</td>
<td>&lt; 1 , V, T_A = 25 , ^\circ C )</td>
<td>0</td>
<td>15</td>
</tr>
<tr>
<td>( I_{IN[1,2]_Leakage} )</td>
<td>Leakage Current from IN[1,2] to OUT</td>
<td>(</td>
<td>V_{IN[1,2]} - V_{OUT}</td>
<td>\leq 5 , V, T_A = 25 , ^\circ C )</td>
<td>-1</td>
<td>--</td>
</tr>
<tr>
<td>( RDS_{ON[1,2]} )</td>
<td>ON Resistance</td>
<td>(</td>
<td>V_{IN[1,2]} - V_{OUT}</td>
<td>\leq 22 , V, T_A = 25 , ^\circ C )</td>
<td>-35</td>
<td>--</td>
</tr>
<tr>
<td>MOSFET ( IDS )</td>
<td>Current from IN[1,2] to OUT</td>
<td>Continuous</td>
<td>--</td>
<td>--</td>
<td>3</td>
<td>A</td>
</tr>
<tr>
<td>( T_{ON_Delay} )</td>
<td>ON Delay Time</td>
<td>( V_{IN<a href="UVLO">1,2</a>} \uparrow ) to V_{OUT} Ramp Start</td>
<td>8</td>
<td>--</td>
<td>--</td>
<td>ms</td>
</tr>
</tbody>
</table>
### Electrical Characteristics (continued)

\( T_A = -40^\circ\text{C} \) to 85 °C, unless otherwise noted.

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Description</th>
<th>Conditions</th>
<th>Min.</th>
<th>Typ.</th>
<th>Max.</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>( V_{OUT(SR)} )</td>
<td>( V_{OUT} ) Slew Rate</td>
<td>10% ( V_{OUT} ) to 90% ( V_{OUT} )</td>
<td></td>
<td>0.3</td>
<td>--</td>
<td>V/ms</td>
</tr>
<tr>
<td></td>
<td></td>
<td>Example: ( C_{SS} = 220 \text{ nF} ), ( V_{IN[1,2]} = 5 \text{ V} ), ( C_{LOAD} = 2 \mu\text{F} ), ( R_{LOAD} = 100 \Omega )</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>( T_{Total_ON} )</td>
<td>Total Turn On Time</td>
<td>( V_{IN<a href="UVLO">1,2</a>} ) ↑ to 90% ( V_{OUT} )</td>
<td></td>
<td>23</td>
<td>--</td>
<td>ms</td>
</tr>
<tr>
<td></td>
<td></td>
<td>Example: ( C_{SS} = 220 \text{ nF} ), ( V_{IN[1,2]} = 5 \text{ V} ), ( C_{LOAD} = 2 \mu\text{F} ), ( R_{LOAD} = 100 \Omega )</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>( V_{PR}, V_{SEL} )</td>
<td>Voltage on PR and SEL pins</td>
<td></td>
<td>0</td>
<td>--</td>
<td>5.5</td>
<td>V</td>
</tr>
<tr>
<td>( V_{ST} )</td>
<td>Voltage on ST pin</td>
<td></td>
<td>0</td>
<td>--</td>
<td>5.5</td>
<td>V</td>
</tr>
<tr>
<td>( V_{OV[1,2]} )</td>
<td>Voltage on OV[1,2] Pins</td>
<td></td>
<td>0</td>
<td>--</td>
<td>5.5</td>
<td>V</td>
</tr>
<tr>
<td>( V_{REF} )</td>
<td>Internal Voltage Reference</td>
<td></td>
<td></td>
<td>1.02</td>
<td>1.06</td>
<td>1.10</td>
</tr>
<tr>
<td></td>
<td></td>
<td>Example: ( C_{SS} = 220 \text{ nF} ), ( V_{PR}, V_{OV1}, V_{OV2}, V_{SEL} ) ↑</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td></td>
<td></td>
<td>( V_{PR}, V_{OV1}, V_{OV2}, V_{SEL} ) ↓</td>
<td></td>
<td>1.00</td>
<td>1.04</td>
<td>1.08</td>
</tr>
<tr>
<td>( I_{Pin_Leakage} )</td>
<td>Pin Leakage Current</td>
<td>( V_{PR}, V_{OV1}, V_{OV2}, V_{ST} ) = 0 V to 5.5 V</td>
<td>-0.1</td>
<td>--</td>
<td>0.1</td>
<td>( \mu\text{A} )</td>
</tr>
<tr>
<td>( I_{ST} )</td>
<td>Status Pin Signal Delay</td>
<td>Transition from Low to High</td>
<td></td>
<td>1</td>
<td>--</td>
<td>( \mu\text{s} )</td>
</tr>
<tr>
<td>( R_{ST} )</td>
<td>Recommended Pull Up Resistance for Status Pin</td>
<td></td>
<td>--</td>
<td>6</td>
<td>20</td>
<td>kΩ</td>
</tr>
<tr>
<td>( I_{RCB} )</td>
<td>Fast Reverse Current Detection Threshold</td>
<td>( V_{OUT} &gt; V_{IN[1,2]} )</td>
<td>0.1</td>
<td>0.5</td>
<td>2</td>
<td>A</td>
</tr>
<tr>
<td>( V_{RCB} )</td>
<td>RCB Release Voltage</td>
<td>( V_{OUT} &gt; V_{IN[1,2]} )</td>
<td>0</td>
<td>25</td>
<td>50</td>
<td>mV</td>
</tr>
<tr>
<td>( I_{RCB} )</td>
<td>Fast Reverse-current Blocking Response Time</td>
<td></td>
<td>--</td>
<td>10</td>
<td>--</td>
<td>( \mu\text{s} )</td>
</tr>
<tr>
<td>( I_{SW} )</td>
<td>Switchover time</td>
<td>( V_{OUT} &lt; V_{IN[1,2]}, V_{SEL} &lt; V_{REF} )</td>
<td>--</td>
<td>100</td>
<td>--</td>
<td>( \mu\text{s} )</td>
</tr>
<tr>
<td>( V_{COMP} )</td>
<td>Input Voltage Comparator</td>
<td>( V_{IN1} \geq V_{IN2} )</td>
<td>0</td>
<td>280</td>
<td>600</td>
<td>mV</td>
</tr>
<tr>
<td></td>
<td>( V_{IN1} &gt; V_{IN2}, \text{Falling Hysteresis} )</td>
<td></td>
<td>2.5</td>
<td>3.5</td>
<td>4.5</td>
<td>%</td>
</tr>
<tr>
<td>( I_{LIMIT} )</td>
<td>Active Current Limit, ( I_{ACL} )</td>
<td></td>
<td>3.0</td>
<td>3.5</td>
<td>4.0</td>
<td>A</td>
</tr>
<tr>
<td></td>
<td>( R_{ILIM} = 31.6 \text{ kΩ} )</td>
<td></td>
<td>3.0</td>
<td>3.5</td>
<td>4.0</td>
<td>A</td>
</tr>
<tr>
<td></td>
<td>( R_{ILIM} = 46.4 \text{ kΩ} )</td>
<td></td>
<td>2.0</td>
<td>2.5</td>
<td>3.0</td>
<td>A</td>
</tr>
<tr>
<td></td>
<td>( R_{ILIM} = 85 \text{ kΩ} )</td>
<td></td>
<td>1.0</td>
<td>1.5</td>
<td>2.0</td>
<td>A</td>
</tr>
<tr>
<td></td>
<td>( R_{ILIM} &lt; 1 \text{ kΩ} )</td>
<td></td>
<td>1.5</td>
<td>2.5</td>
<td>3.5</td>
<td>A</td>
</tr>
<tr>
<td>( I_{LIMIT}^2 )</td>
<td>Current Limit Response Time</td>
<td>From ( I_{DS} &gt; I_{ACL} ) to ( I_{DS} ) regulated to ( I_{ACL} )</td>
<td>--</td>
<td>250</td>
<td>--</td>
<td>( \mu\text{s} )</td>
</tr>
<tr>
<td>( THERM_{ON} )</td>
<td>Thermal shutoff turn-on temperature</td>
<td></td>
<td>--</td>
<td>160</td>
<td>--</td>
<td>°C</td>
</tr>
<tr>
<td>( THERM_{OFF} )</td>
<td>Thermal shutoff turn-off temperature</td>
<td></td>
<td>--</td>
<td>140</td>
<td>--</td>
<td>°C</td>
</tr>
<tr>
<td>( THERM_{TIME}^3 )</td>
<td>Thermal shutoff time</td>
<td></td>
<td>--</td>
<td>--</td>
<td>1</td>
<td>ms</td>
</tr>
</tbody>
</table>

Notes:
1. Refer to typical Timing Parameter vs. \( C_{SS} \) performance charts for additional information when available.
2. For more information on device behavior during short-circuit conditions please see SLG59H1403C Current Limiting section.
3. See Current Limit Behavior Timing Diagram
SLG59H1403C Normal Operation State Table

<table>
<thead>
<tr>
<th>Mode</th>
<th>Condition</th>
<th>PR ≥ V_{REF}</th>
<th>SEL ≥ V_{REF}</th>
<th>OUT</th>
<th>ST</th>
<th>Note</th>
</tr>
</thead>
<tbody>
<tr>
<td>VCOMP mode</td>
<td>IN1 &gt; IN2</td>
<td>0</td>
<td>0</td>
<td>IN1</td>
<td>H</td>
<td>Largest Input Voltage Determines Output</td>
</tr>
<tr>
<td>VCOMP mode</td>
<td>IN1 ≤ IN2</td>
<td>0</td>
<td>0</td>
<td>IN2</td>
<td>L</td>
<td>Largest Input Voltage Determines Output</td>
</tr>
<tr>
<td>Priority mode</td>
<td>X</td>
<td>1</td>
<td>0</td>
<td>IN1</td>
<td>H</td>
<td>Select Channel 1 on OUT as priority</td>
</tr>
<tr>
<td>Manual Channel</td>
<td>X</td>
<td>X</td>
<td>1</td>
<td>IN2</td>
<td>L</td>
<td>Override priority and select Channel 2 on OUT</td>
</tr>
<tr>
<td>Selection mode</td>
<td>X</td>
<td>X</td>
<td>1</td>
<td></td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

SLG59H1403C Fault Operation State Table

<table>
<thead>
<tr>
<th>Channel 1 Fault</th>
<th>Channel 2 Fault</th>
<th>SEL ≥ V_{REF}</th>
<th>OUT</th>
<th>ST</th>
<th>Note</th>
</tr>
</thead>
<tbody>
<tr>
<td>IN1 ≤ V_{IN1(UVLO)} Or OV1 ≥ V_{REF}</td>
<td>IN2 ≤ V_{IN2(UVLO)} Or OV2 ≥ V_{REF}</td>
<td>X</td>
<td>-</td>
<td>-</td>
<td>Output Behavior Determined by &quot;Normal Operation State&quot; Table</td>
</tr>
<tr>
<td>0</td>
<td>0</td>
<td>X</td>
<td>-</td>
<td>-</td>
<td></td>
</tr>
<tr>
<td>1</td>
<td>0</td>
<td>X</td>
<td>IN2</td>
<td>L</td>
<td>Channel 1 is not valid, switch to Channel 2</td>
</tr>
<tr>
<td>0</td>
<td>1</td>
<td>0</td>
<td>IN1</td>
<td>H</td>
<td>Channel 2 is not valid, switch to Channel 1</td>
</tr>
<tr>
<td>1</td>
<td>1</td>
<td>0</td>
<td></td>
<td>H</td>
<td>Channel 1 and Channel 2 are not valid, output is in Hi-Z state</td>
</tr>
<tr>
<td>X</td>
<td>1</td>
<td>1</td>
<td></td>
<td>H</td>
<td>Selected Channel 2 is not valid, output is in Hi-Z state</td>
</tr>
</tbody>
</table>

A summary of the SLG59H1403C device operation:

- If the valid voltages are applied at both inputs and PR is higher than V_{REF}, then IN1 will power the output.
- If the valid voltages are applied at both inputs and PR is lower than V_{REF}, then the highest input voltage will power the output.
- If both inputs are not valid, then the output is Hi-Z.
- ST pin indicates which of the inputs is powering output. ST pulled high when IN1 is powering the output or the output is Hi-Z. ST pulled low when IN2 is powering the output.
- SEL pin can override the PR. When SEL is pulled high IN2 is powering the output.
Timing Diagrams

VCOMP Mode operating timing diagram

- **IN1**
  - Voltage: 0 V
  - **V<sub>IN1(UVLO)</sub>**
  - **V<sub>IN1 - V<sub>COMP</sub></sub>**
  - **Hysteresis**

- **IN2**
  - Voltage: 0 V

- **SEL**
  - Voltage: 0 V

- **PR**
  - Voltage: 0 V

- **SS**
  - Voltage: 0 V

- **OUT**
  - Voltage: 0 V
  - **V<sub>OUT(SR)</sub>**
  - **t<sub>SW</sub>**

### Timing Parameters
- **T<sub>TOT.ON</sub>**
- **T<sub>ON_DELAY</sub>**
- **V<sub>IN1 - Fixed Drop</sub>/V<sub>OUT(SR)</sub>**
- **Delay time = (V<sub>IN1 - Fixed Drop</sub>/V<sub>OUT(SR)</sub>) or 0.5 V - 0.6 V Fixed Drop**

### Voltage Levels
- 0 V
- 3.3 V
- 5 V
- 10%
- 90%
- 0.5 V - 0.6 V

### Notes
- **Fixed Drop**
- **Delay Time Calculation**
- **Hysteresis**
Switchover operating timing diagram by PR signal

- **IN1**
- **IN2**
- **SEL**
- **PR**
- **OUT**

- Time

---

V<sub>RCB</sub> 0.5 V - 0.6 V Fixed Drop

- 0.5 V - 0.6 V Fixed Drop

- 0.5 V - 0.6 V Fixed Drop

- 0.5 V - 0.6 V Fixed Drop
Switchover operating timing diagram by SEL signal

\[
\text{Delay time} = \frac{(V_{IN1} - \text{Fixed Drop})}{V_{OUT(SR)}}
\]
Current Limit Behavior Timing Diagram

- **OV**
- **I_DS**
- **OUT**
- **ST**
- **T_J**
- **THERM_ON**
- **THERM_OFF**

Overload Condition, Auto Restart Into Overload, Auto Restart (Overload Removed)

**THERM_TIME**

Time
**Typical Performance Characteristics**

$T_{\text{Total_ON}}$ vs $C_{\text{SS}}$, $V_{\text{IN}[1,2]}$, and Temperature

![Graph showing $T_{\text{Total_ON}}$ vs $C_{\text{SS}}$, $V_{\text{IN}[1,2]}$, and Temperature.](image)

$V_{\text{OUT}}$ Slew Rate vs $C_{\text{SS}}$, $V_{\text{IN}[1,2]}$, and Temperature

![Graph showing $V_{\text{OUT}}$ Slew Rate vs $C_{\text{SS}}$, $V_{\text{IN}[1,2]}$, and Temperature.](image)
Typical Turn ON Operation Waveforms

Figure 1. Typical Turn ON operation waveform for $V_{\text{IN1}} = 5\, \text{V}$, $C_{\text{SS}} = 220\, \text{nF}$, $R_{\text{LOAD}} = 100\, \Omega$, $C_{\text{LOAD}} = 2\, \mu\text{F}$

Figure 2. Typical Turn ON operation waveform for $V_{\text{IN1}} = 12\, \text{V}$, $C_{\text{SS}} = 220\, \text{nF}$, $R_{\text{LOAD}} = 100\, \Omega$, $C_{\text{LOAD}} = 2\, \mu\text{F}$
Figure 3. Typical Turn ON operation waveform for $V_{IN1} = 22\, \text{V}$, $C_{SS} = 220\, \text{nF}$, $R_{LOAD} = 100\, \Omega$, $C_{LOAD} = 2\, \mu\text{F}$

Figure 4. Typical Turn ON operation waveform for $V_{IN2} = 5\, \text{V}$, $C_{SS} = 220\, \text{nF}$, $R_{LOAD} = 100\, \Omega$, $C_{LOAD} = 2\, \mu\text{F}$
Figure 5. Typical Turn ON operation waveform for $V_{IN2} = 12\, V$, $C_{SS} = 220\, \text{nF}$, $R_{LOAD} = 100\, \Omega$, $C_{LOAD} = 2\, \mu\text{F}$

Figure 6. Typical Turn ON operation waveform for $V_{IN2} = 22\, V$, $C_{SS} = 220\, \text{nF}$, $R_{LOAD} = 100\, \Omega$, $C_{LOAD} = 2\, \mu\text{F}$
Switchover Operation Waveforms

**Figure 7.** Switchover operation waveform for $V_{IN1} = 12$ V, $V_{IN2} = 5$ V, $C_{SS} = 220$ nF, $PR = 0$ V, $SEL = $ Low -> High, $R_{LOAD} = 100$ Ω, $C_{LOAD} = 2$ μF

**Figure 8.** Switchover operation waveform for $V_{IN1} = 12$ V, $V_{IN2} = 5$ V, $C_{SS} = 220$ nF, $PR = 0$ V, $SEL = $ High -> Low, $R_{LOAD} = 100$ Ω, $C_{LOAD} = 2$ μF
Figure 9. Switchover operation waveform for $V_{IN1} = 3$ V, $V_{IN2} = 4$ V, $C_{SS} = 220$ nF, SEL = 0 V, PR = Low -> High, $R_{LOAD} = 100$ Ω, $C_{LOAD} = 2$ μF.

Figure 10. Switchover operation waveform for $V_{IN1} = 3$ V, $V_{IN2} = 4$ V, $C_{SS} = 220$ nF, SEL = 0 V, PR = High -> Low, $R_{LOAD} = 100$ Ω, $C_{LOAD} = 2$ μF.
Higher Voltage Level Priority Operation Waveforms

Figure 11. Higher voltage level priority operation waveform for
\( V_{IN1} = 3.3 \, V, V_{IN2} = 5 \, V, \, SEL = 0 \, V, \, PR = 0 \, V, \, C_{SS} = 220 \, nF, \, R_{LOAD} = 100 \, \Omega, \, C_{LOAD} = 2 \, \mu F \)

Figure 12. Higher voltage level priority operation waveform for
\( V_{IN1} = 3.3 \, V, V_{IN2} = 5 \, V, \, SEL = 0 \, V, \, PR = 0 \, V, \, C_{SS} = 220 \, nF, \, R_{LOAD} = 100 \, \Omega, \, C_{LOAD} = 2 \, \mu F \) (Extended View)
Figure 13. Higher voltage level priority operation waveform for $V_{IN1} = 5\, \text{V}$, $V_{IN2} = 3.3\, \text{V}$, $SEL = 0\, \text{V}$, $PR = 0\, \text{V}$, $C_{SS} = 220\, \text{nF}$, $R_{LOAD} = 100\, \Omega$, $C_{LOAD} = 2\, \mu\text{F}$

Figure 14. Higher voltage level priority operation waveform for $V_{IN1} = 5\, \text{V}$, $V_{IN2} = 3.3\, \text{V}$, $SEL = 0\, \text{V}$, $PR = 0\, \text{V}$, $C_{SS} = 220\, \text{nF}$, $R_{LOAD} = 100\, \Omega$, $C_{LOAD} = 2\, \mu\text{F}$ (Extended View)
Active Current Limit Operation Waveforms

Figure 15. Test setup for Active Current Limit Operation

Figure 16. <>

\[ R_{LOAD} = 0.68 \, \Omega, \quad C_{LOAD} = 2 \, \mu F \]
Figure 17. <>
\[ R_{LOAD} = 1.1 \, \Omega, \quad C_{LOAD} = 2 \, \mu F \]

Figure 18. <>
\[ R_{LOAD} = 2.2 \, \Omega, \quad C_{LOAD} = 2 \, \mu F \]
Figure 19. $R_{LOAD} = 4.2 \, \Omega$, $C_{LOAD} = 2 \, \mu F$

Figure 20. $R_{LOAD} = 4.2 \, \Omega$, $C_{LOAD} = 2 \, \mu F$ (Extended View)
APPLICATIONS INFORMATION

SLG59H1403C Power-Up Considerations

Once \( V_{IN1} \) voltage is valid (\( V_{IN1} > V_{IN1(UVLO)} \) and \( V_{IN1} < \) Overvoltage lockout level set by OV1) and has priority under \( V_{IN2} \), a turn on delay (\( T_{ON\_Delay} \)) will occur and then, for soft start, output voltage start rising with slew rate (\( V_{OUT(SR)} \)) set by \( C_{SS} \) capacitor. After the total turn on time (\( T_{Total\_ON} \)), soft start will not be used again for \( V_{IN1} \) until it becomes not valid (\( V_{IN1} < V_{IN1(UVLO)} \) or \( V_{IN1} > \) Overvoltage lockout level set by OV1). When \( V_{IN2} \) voltage becomes valid (\( V_{IN2} > V_{IN2(UVLO)} \) and \( V_{IN2} < \) Overvoltage lockout level set by OV2) and \( V_{SEL} > V_{REF} \), a turn on delay (\( T_{ON\_Delay} \)) will occur again and then, for soft start, output voltage start rising with slew rate (\( V_{OUT(SR)} \)) set by \( C_{SS} \) capacitor. After the total turn on time (\( T_{Total\_ON} \)), soft start will not be used again for \( V_{IN2} \) until it becomes not valid (\( V_{IN2} < V_{IN2(UVLO)} \) or \( V_{IN2} > \) Overvoltage lockout level set by OV2). If \( V_{IN2} \) becomes valid and selected before \( V_{OUT} \) ends rising with \( V_{IN1} \), the \( V_{OUT} \) switching procedure to \( V_{IN2} \) will start after \( V_{OUT} \) rising has ended with \( V_{IN1} \).

This is an example of power up procedure when \( V_{IN1} \) is applied before \( V_{IN2} \). In case \( V_{IN2} \) is applied before \( V_{IN1} \) the procedure will be similar.

Soft Start introduction

The output voltage slew rate can be configured by changing the \( C_{SS} \) capacitance. The Table below shows the typical slew rate and \( T_{Total\_ON} \) time across \( C_{SS} \) capacitance, \( V_{IN[1,2]} \), and Temperature from -40 °C to 85 °C for \( R_{LOAD} = 100 \Omega \) and \( C_{LOAD} = 2 \mu F \).

<table>
<thead>
<tr>
<th>( C_{SS}, \mu F )</th>
<th>( V_{OUT(SR)}, \text{V} / \text{ms} )</th>
<th>( T_{Total_ON}, \text{ms} )</th>
</tr>
</thead>
<tbody>
<tr>
<td>( V_{IN[1,2]} = 2.8 \text{ V to 22 V} )</td>
<td>( V_{IN[1,2]} = 2.8 \text{ V} )</td>
<td>( V_{IN[1,2]} = 5.0 \text{ V} )</td>
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<tr>
<td>0.1</td>
<td>0.67</td>
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<tr>
<td>1.0</td>
<td>0.077</td>
<td>45</td>
</tr>
</tbody>
</table>

Resistor Divider Calculations for Overvoltage Protection and Operating Mode Selection

To set the overvoltage threshold for OV1 and OV2, and \( V_{PR} \) and \( V_{SEL} \) levels, a typical voltage divider, illustrated in Figure 21 is used.

![Figure 21. Typical Resistive Voltage Divider](image_url)
In order to calculate the voltage divider, the equation below is used

\[ R_1 = \frac{R_2 \times (V_{IN[1,2]} - V_{REF})}{V_{REF}} \]

where:
- \( R_1 \) = calculated resistor value in kΩ;
- \( R_2 \) = resistor closest to ground. Recommended \( R_2 \) value is 5 kΩ;
- \( V_{IN[1,2]} \) = \( V_{IN1} \) or \( V_{IN2} \) voltage level at which protection should be triggered;
- \( V_{REF} \) = Internal voltage reference for OV1, OV2, PR and SEL pins.

### Using SLG59H1403C in OR’ing applications

In the case of OR’ing two supplies, if both power rails are valid, then the higher voltage is passed to the output. If one of the power rails suddenly disappears, then output OUT is automatically switched to the other available power rail. If both power rails have equal voltage levels, then based on the \( V_{COMP} \) spec, IN2 has higher priority and will be switched to OUT. If \( V_{IN2} \) falls below the \( V_{COMP} \) Hysteresis, then IN1 will switch to OUT. To set SLG59H1403C in OR’ing mode, connect the PR and SEL pins to GND or \( V_{PR} \) and \( V_{SEL} \) should be < \( V_{REF} \).

OV1 and OV2 with external resistors connected to IN1 and IN2 respectively can be configured to provide overvoltage protection.

The ST pin can be pulled high with a resistor to provide feedback on the status of the system. If the ST pin is high, IN1 is the output or the output is Hi-Z. If the ST pin is low, IN2 is the output.
Figure 23. Connection diagram of using SLG59H1403C in OR'ing applications
Using SLG59H1403C in manual power rail selection applications

In the case of using the SLG59H1403C in a manual power rail selection application, an external voltage ≥ $V_{REF}$ should be applied at the PR pin through a pull up resistor. If $V_{PR} \geq V_{REF}$ and $V_{SEL} < V_{REF}$, then IN1 will be selected. By toggling $V_{SEL} \geq V_{REF}$, IN2 will be selected.

OV1 and OV2 with external resistors connected to IN1 and IN2 respectively can be configured to provide overvoltage protection. The ST pin can be pulled high with a resistor to provide feedback on the status of the system. If the ST pin is high, IN1 will be at output or the output is Hi-Z. If the pin is low, IN2 will be at output.

![Connection diagram](image)

**Figure 24. Connection diagram of using SLG59H1403C in manual power rail selection applications**

Using SLG59H1403C in manual power rail selection applications with priority

In the case of using SLG59H1403C in applications where automatic and manual switching is required, the PR pin must be connected through an additional voltage divider (R5, R6) to IN1. The typical connection diagram for this application is illustrated in Figure 25. When $V_{IN1}$ falls to induce $V_{PR} < V_{REF}$ and $V_{SEL} < V_{REF}$, SLG59H1403C will operate in VCOMP mode and largest voltage will be on the output. If $V_{SEL} \geq V_{REF}$ then IN2 will be selected.

OV1 and OV2 with external resistors are connected to IN1 and IN2 respectively and can be configured to provide overvoltage protection.

The ST pin can be pulled high with a resistor to provide feedback on the status of the system. If the ST pin is high, IN1 will be at the output or the output is Hi-Z. If the pin is low, IN2 will be at the output.
An alternative connection diagram with a common voltage divider $R_1$, $R_2$, $R_3$ shown in Figure 26 can be used but caution must be used to make sure that the voltage on the PR and OV1 pins will not exceed the Absolute Maximum Ratings spec, otherwise SLG59H1403C can be damaged. If this condition cannot be met, separate voltage dividers shown in Figure 25 should be used instead.
Resistor divider for this type of application solution is calculated in two steps:

1. Calculate voltage divider section for OV1 threshold:

\[
R_{\text{COMMON}} = \frac{R3 \times (V_{IN1} - V_{\text{REF}})}{V_{\text{REF}}}
\]

where:

- \( R_{\text{COMMON}} \) = calculated common resistance value for \( R1 + R2 \) in kΩ;
- \( R3 \) = resistor closest to ground. Recommended \( R3 \) value is 5 kΩ;
- \( V_{IN1} \) = \( V_{IN1} \) voltage at which overvoltage protection should be triggered;
- \( V_{\text{REF}} \) = Internal voltage reference for OV1 pin.

2. Calculate voltage divider section for priority threshold:

\[
R1 = \frac{(R_{\text{COMMON}} + R3) \times (V_{IN1} - V_{\text{REF}})}{V_{IN1}}
\]

\[
R2 = R_{\text{COMMON}} - R1
\]
where:
\( R_{\text{COMMON}} \) = calculated common resistance value for R1 + R2 in k\( \Omega \);
R1, R2 = resistors near PR pin;
R3 = resistor closest to ground. Recommended R3 value is 5 k\( \Omega \);
\( V_{\text{IN1}} \) = \( V_{\text{IN1}} \) voltage at which PR threshold should be triggered;
\( V_{\text{REF}} \) = Internal voltage reference for OV1 and PR pins.

**SLG59H1403C Current Limiting**

The SLG59H1403C has two modes of current limiting

1. **Standard Current Limiting Mode (with Thermal Protection)**

   The output current is initially limited to the Active Current Limit specification given in the Electrical Characteristics table. The current limiting circuit is very fast and responds within a few microseconds to sudden loads. When overload is sensed, the current limiting circuit increases the FET resistance to keep the current from exceeding the Active Current Limit.

   The ACL level can be adjusted by choosing the appropriate ±1%-tolerance \( R_{\text{ILIM}} \) value and can be calculated by the following equations:

   For \( R_{\text{ILIM}} \) range from 31.6 k\( \Omega \) to 100 k\( \Omega \):

   \[
   I_{\text{ACL}} = \frac{69.1}{R_{\text{ILIM}}^{0.861}}
   \]

   where:

   \( R_{\text{ILIM}} \) = Resistor on ILIM pin, in kOhms (k\( \Omega \))

   However, if an overload condition persists, the die temperature rise due to the increased FET resistance while at maximum current can activate Thermal Protection. If the die temperature exceeds the \( T_{\text{HERM}_{\text{ON}}} \) specification, the FET is shut completely OFF, allowing the die to cool. When the die cools to the \( T_{\text{HERM}_{\text{OFF}}} \) temperature, the FET is allowed to turn back on. This process may repeat as long as the overload condition is present.

2. **Short Circuit Current Limiting Mode (with Thermal Protection)**

   In the case of a hard short (\( R_{\text{SHORT}} \geq 0.5 \Omega \)), such as a solder bridge on the power rail, the current is limited to protect the chip. Thermal Protection is also present and may be activated during Short Circuit Current Limit protection operation.
Fast Reverse Current Blocking (RCB)

Each channel has Always ON Reverse Current Blocking. If the output is forced above the selected input by $V_{IRCB}$, the channel will switch off to stop the reverse current $I_{RCB}$ within $t_{RCB}$. As the output falls to within the $V_{RCB}$ of $V_{IN}$, the selected channel will quickly turn back on to avoid unnecessary voltage drops during fast switchover ($t_{SW}$).

![Figure 27. Reverse Current Blocking Behavior](image)
Power Dissipation

The junction temperature of the SLG59H1403C depends on factors such as board layout, ambient temperature, external air flow over the package, load current, and the $R_{DS\,ON}$-generated voltage drop across each load switch. While the primary contributor to the increase in the junction temperature of the SLG59H1403C is the power dissipation of its load switches, its power dissipation and the junction temperature in nominal operating mode can be calculated using the following equations:

$$PD_{TOTAL} = (R_{DS\,ON[1,2]} \times I_{DS[1,2]}^2)$$

where:
- $PD_{TOTAL}$ = Total package power dissipation, in Watts (W)
- $R_{DS\,ON[1,2]}$ = Channel 1 and Channel 2 load switch ON resistance, in Ohms (Ω), respectively
- $I_{DS[1,2]}$ = Channel 1 and Channel 2 Output current, in Amps (A), respectively

and

$$T_J = PD_{TOTAL} \times \theta_{JA} + T_A$$

where:
- $T_J$ = Die junction temperature, in Celsius degrees (°C)
- $\theta_{JA}$ = Package thermal resistance, in Celsius degrees per Watt (°C/W) – highly dependent on pcb layout
- $T_A$ = Ambient temperature, in Celsius degrees (°C)

In nominal operating mode, the SLG59H1403C’s power dissipation can also be calculated by taking into account the voltage drop across each load switch ($V_{IN[1,2]} - V_{OUT}$) and the magnitude of that channel’s output current ($I_{DS[1,2]}$):

$$PD_{TOTAL} = (V_{IN[1,2]} - V_{OUT}) \times I_{DS[1,2]}$$

where:
- $PD_{TOTAL}$ = Total package power dissipation, in Watts (W)
- $V_{IN[1,2]}$ = Channel 1 and Channel 2 Input Voltage, in Volts (V), respectively
- $R_{LOAD}$ = Output Load Resistance, in Ohms (Ω)
- $I_{DS[1,2]}$ = Channel 1 and Channel 2 output current, in Amps (A), respectively
- $V_{OUT}$ = Output voltage, or $R_{LOAD} \times I_{DS[1,2]}$
Layout Guidelines:

1. Since the IN[1,2] and OUT pins dissipate most of the heat generated during high-load current operation, it is highly recommended to make power traces as short, direct, and wide as possible. A good practice is to make power traces with an absolute minimum widths of 15 mils (0.381 mm) per Ampere. A representative layout, shown in Figure 28, illustrates proper techniques for heat to transfer as efficiently as possible out of the device;

2. To minimize the effects of parasitic trace inductance on normal operation, it is recommended to connect input $C_{IN[1,2]}$ and output $C_{LOAD}$ low-ESR capacitors as close as possible to the SLG59H1403C's IN[1,2] and OUT pins;

3. The GND pin should be connected to system analog or power ground plane.

SLG59H1403C Evaluation Board:

A High Voltage GreenFET Evaluation Board for SLG59H1403C is designed according to the statements above and is illustrated on Figure 28. Please note that evaluation board has IN[1,2]_Sense and OUT_Sense pads. They cannot carry high currents and dedicated only for RDS$_{ON[1,2]}$ evaluation.

Figure 28. SLG59H1403C Evaluation Board
Basic EVB Configuration

1. Connect oscilloscope probes to IN[1,2], OUT, ST etc.;
2. Connect jumpers on X1-X3 and X4-X6 to configure overvoltage protection threshold for Channel 1 and Channel 2 respectively. Jumpers for OV[1,2] Settings sets the typical operating input voltage, and the overvoltage protection threshold will be 20% higher than that setting. For example, if jumper for OV1 Settings is located at 3.3 V position – overvoltage threshold is 3.96 V, and etc.
3. Connect jumpers on X7-X9 to configure the PR level. Jumper for PR Settings sets the typical operating input voltage in Priority mode. If the input voltage falls below the typical operating voltage level by around 4%...5%, V_{PR} will be lower than V_{REF} and SLG59H1403C will operate in VCOMP mode.
4. Configure SS and ILIM using X20 and X21 respectively. For more information, please refer to the Soft start introduction section and SLG59H1403C Current Limiting section in this Datasheet.
5. Select the desired operation mode using X15, X22 and connect a Pull-Up resistor to ST pin using X16. For more information regarding different operation modes please refer to the SLG59H1403C Normal Operation State Table in this datasheet.
6. Logic High for the SEL pin configuration is connected to the PR pin signal. This means that in order to apply a High state to the SEL pin, it needs to apply logic High to the PR signal first. Such a configuration allows it to work in manual channel selection mode to switchover between Channel 1 and Channel 2 regardless of voltage levels on V_{IN[1,2]}.
## Package Top Marking System Definition

<table>
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<tr>
<th>Part Code</th>
<th>Date Code + Serial Code</th>
<th>Pin 1 Identifier + Assembly Code + Revision Code</th>
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<tr>
<td>P P P P P P</td>
<td>Y W N N N N N N N N</td>
<td>A R R</td>
</tr>
</tbody>
</table>
Package Drawing and Dimensions

20 Lead WLCSP Package 1.985 mm x 1.585 mm

Symbol | Dimensions in mm | Dimensions in inch
-------|-----------------|------------------
A | 0.4400 | 0.4700 | 0.5000 | 0.0173 | 0.0185 | 3.0197
A1 | 0.1500 | 0.1650 | 0.1800 | 0.0059 | 0.0065 | 3.0071
b | 0.1950 | 0.2250 | 0.2550 | 0.0077 | 0.0089 | 3.0100
D1 | --- | 1.2000 | --- | --- | 0.0472 | ---
D2 | --- | 0.1925 | --- | --- | 0.0076 | ---
D3 | --- | 0.1925 | --- | --- | 0.0076 | ---
E1 | --- | 1.6000 | --- | --- | 0.0630 | ---
E2 | --- | 0.1925 | --- | --- | 0.0076 | ---
E3 | --- | 0.1925 | --- | --- | 0.0076 | ---
E | --- | 0.4000 | --- | --- | 0.0157 | ---
aaa | --- | 0.025 | --- | --- | 0.001 | ---
bbb | --- | 0.06C | --- | --- | 0.002 | ---
ccc | --- | 0.03C | --- | --- | 0.001 | ---
ddd | --- | 0.05C | --- | --- | 0.002 | ---
eee | --- | 0.050 | --- | --- | 0.002 | ---

NOTE:
1. CONTROLLING DIMENSION IS MILLIMETER

2. DIMENSION IS MEASURED AT THE MAXIMUM SOLID BALL DIAMETER, PARALLEL TO PRIMARY DATUM C

3. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLID BALLS

4. THE SOLID BALL SIZE PRIOR TO REWORK IS 210 UM
Recommended Landing Pattern

Units: mm

Solder mask detail (not to scale)
Tape and Reel Specifications

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<th>Package Type</th>
<th># of Pins</th>
<th>Nominal Package Size</th>
<th>Units per Reel</th>
<th>Max Units per Box</th>
<th>Reel &amp; Hub Size (mm)</th>
<th>Trailer A</th>
<th>Leader B</th>
<th>Pocket Tape (mm)</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td></td>
<td></td>
<td>Max Units per Box</td>
<td></td>
<td></td>
<td>Pockets</td>
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<td>Pockets</td>
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<tr>
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Carrier Tape Drawing and Dimensions

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<th>Pocket Pitch [mm]</th>
<th>Index Hole Pitch [mm]</th>
<th>Pocket Diameter [mm]</th>
<th>Index Hole to Tape Edge [mm]</th>
<th>Index Hole to Pocket Center [mm]</th>
<th>Tape Width [mm]</th>
<th>Tape Thickness [mm]</th>
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<td>4</td>
<td>1.5</td>
<td>1.75</td>
<td>3.5</td>
<td>8</td>
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Note: 1. Orientation in carrier: Pin1 is at upper left corner (Quadrant 1).

Recommended Reflow Soldering Profile

Please see IPC/JEDEC J-STD-020: latest revision for reflow profile based on package volume of 0.9595 mm³ (nominal). More information can be found at www.jedec.org.
Revision History

<table>
<thead>
<tr>
<th>Date</th>
<th>Version</th>
<th>Change</th>
</tr>
</thead>
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<tr>
<td>25-Aug-2022</td>
<td>1.01</td>
<td>Fixed Pin Description for IN1</td>
</tr>
<tr>
<td>15-Jul-2022</td>
<td>1.0</td>
<td>Production Release</td>
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